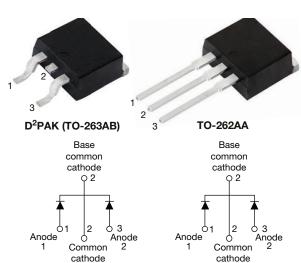
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COMPLIANT HALOGEN

**FREE** 

# Ultrafast Rectifier, 2 x 10 A FRED Pt®



#### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS							
I <sub>F(AV)</sub>	2 x 10 A						
V <sub>R</sub>	200 V						
V <sub>F</sub> at I <sub>F</sub>	0.85						
t <sub>rr</sub> typ.	19 ns						
T <sub>J</sub> max.	175 °C						
Package	D <sup>2</sup> PAK (TO-263AB), TO-262AA						
Circuit configuration	Common cathode						

#### **FEATURES**

- Ultrafast recovery time
- Low forward voltage drop
- · Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Meets JESD 201 class 1 whisker test
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

#### **DESCRIPTION / APPLICATIONS**

MUR.. series are the state of the art ultrafast recovery rectifiers specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

#### **MECHANICAL DATA**

Case: D<sup>2</sup>PAK (TO-263AB), TO-262AA

Molding compound meets UL 94 V-0 flammability rating

**Terminals:** matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS					
Peak repetitive reverse voltage	$V_{RRM}$		200	V					
Average restified forward august	per leg		10						
Average rectified forward current total	device I <sub>F(AV)</sub>	Rated V <sub>R</sub> , T <sub>C</sub> = 145 °C	20						
Non-repetitive peak surge current per leg	I <sub>FSM</sub>		100	А					
Peak repetitive forward current per leg	I <sub>FM</sub>	Rated V <sub>R</sub> , square wave, 20 kHz, T <sub>C</sub> = 145 °C	20						
Operating junction and storage temperature	es T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C					

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER SYMBOL TEST CONDITIONS		TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	$V_{BR}, V_{R}$	$I_{R} = 100 \ \mu A$	200	-	-				
		I <sub>F</sub> = 8 A, T <sub>J</sub> = 125 °C	-	-	0.85	V			
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 16 A	-	-	1.15	\ \ \			
		I <sub>F</sub> = 16 A, T <sub>J</sub> = 125 °C	-	-	1.05				
Reverse leakage current	1_	$V_R = V_R$ rated	-	-	15				
neverse leakage current	I <sub>R</sub>	$T_J = 150 ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	-	250	μA			
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V	-	55	-	pF			
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ			

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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1.0 \text{ A}, dI_F/dt =$	100 A/ $\mu$ s, V <sub>R</sub> = 30 V	-	19	-			
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	21	-	ns A nC		
		T <sub>J</sub> = 125 °C	$I_F = 10 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 160 \text{ V}$	-	35	-			
Poak rocoveny current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	1.9	-			
Peak recovery current		T <sub>J</sub> = 125 °C		-	4.8	-			
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		ı	25	-			
		T <sub>J</sub> = 125 °C		-	78	-			

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C			
Thermal resistance, junction to case per leg	R <sub>thJC</sub>		-	-	2.5				
Thermal resistance, junction to ambient per leg	R <sub>thJA</sub>		-	-	50	°C/W			
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.5	-				
Weight			-	2.0	-	g			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Maulden de de		Case style D <sup>2</sup> PAK (TO-263AB)		MURB2	2020CTH	•			
Marking device		Case style TO-262		MURB20	020CT-1H				

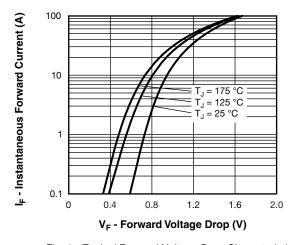


Fig. 1 - Typical Forward Voltage Drop Characteristics

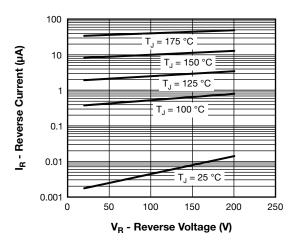


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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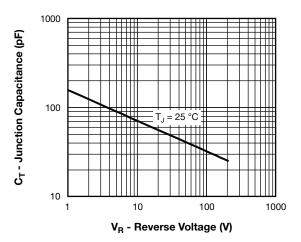


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

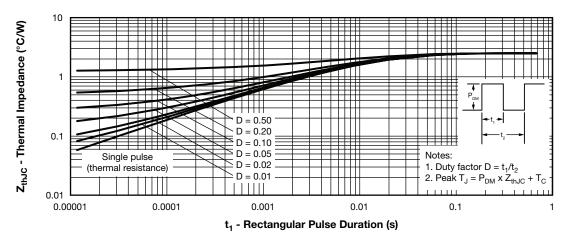


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

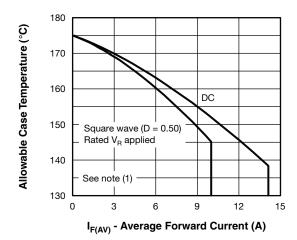


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

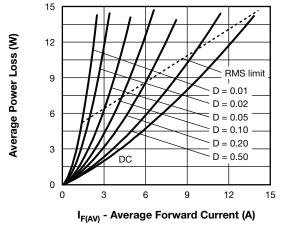


Fig. 6 - Forward Power Loss Characteristics

#### Note

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<sup>(1)</sup> Formula used: T<sub>C</sub> = T<sub>J</sub> - (Pd + Pd<sub>REV</sub>) x R<sub>thJC</sub>; Pd = Forward power loss = I<sub>F(AV)</sub> x V<sub>FM</sub> at (I<sub>F(AV)</sub>/D) (see fig. 6); Pd<sub>REV</sub> = Inverse power loss = V<sub>R1</sub> x I<sub>R</sub> (1 - D); I<sub>R</sub> at V<sub>R1</sub> = Rated V<sub>R</sub>

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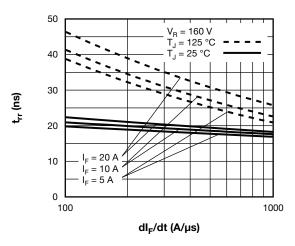


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

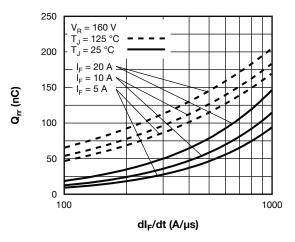
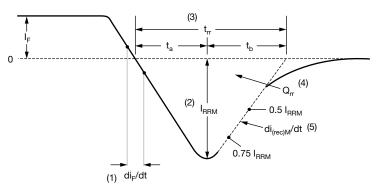


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{\text{RRM}}$  peak reverse recovery current
- (3) t<sub>rr</sub> reverse recovery time measured from zero crossing point of negative going I<sub>F</sub> to point where a line passing through 0.75 I<sub>RBM</sub> and 0.50 I<sub>RBM</sub> extrapolated to zero current.
- (4)  $Q_{rr}$  area under curve defined by  $t_{rr}$  and  $I_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

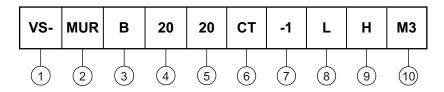
(5) di<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 9 - Reverse Recovery Waveform and Definitions

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#### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

2 - Ultrafast MUR series

- B = D<sup>2</sup>PAK/TO-262

4 - Current rating (20 = 20 A)

5 - Voltage rating (20 = 200 V)

6 - CT = Center tap (dual) TO-220/D<sup>2</sup>PAK/TO-262

7 - • -1 = TO-262

None = D<sup>2</sup>PAK

8 - • None

• L = Tape and reel (left oriented, for D<sup>2</sup>PAK package)

• R = Tape and reel (right oriented, for D<sup>2</sup>PAK package)

9 - H = AEC-Q101 qualified

- M3 = Halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-MURB2020CTHM3	50	Antistatic plastic tube					
VS-MURB2020CT-1HM3	50	Antistatic plastic tube					
VS-MURB2020CTLHM3	800	13" diameter reel					
VS-MURB2020CTRHM3	800	13" diameter reel					

LINKS TO RELATED DOCUMENTS						
Dimensions	TO-263AB (D <sup>2</sup> PAK)	www.vishay.com/doc?95046				
Difficusions	TO-262AA	www.vishay.com/doc?95419				
Don't manufacture information	TO-263AB (D <sup>2</sup> PAK)	www.vishay.com/doc?95444				
Part marking information	TO-262AA	www.vishay.com/doc?95443				
Packaging information	TO-263AB (D <sup>2</sup> PAK)	www.vishay.com/doc?95032				
SPICE model		www.vishay.com/doc?96995				



### Vishay Semiconductors

## D<sup>2</sup>PAK

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES		SYMBOL		ETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	) BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

#### Notes

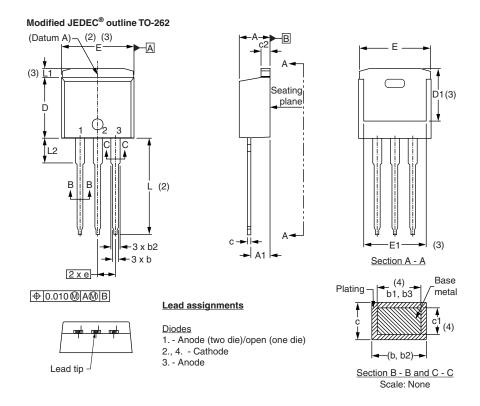
- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



### Vishay Semiconductors

### **TO-262**

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	BSC	0.10	D BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.71	0.132	0.146	

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

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